Item	Designator	Description	Manufacturer	PartNumber	Quantity
1	C1	CAP, Film, 0.047uF, 310Vac, +/-10%, TH	Vishay	BFC233920473	1
2	C2, C8	CAP, CERM, 10uF, 50V, +/-10%, X7R, 1210	MuRata	GRM32ER71H106KA12L	2
3	C3	CAP, CERM, 2.2uF, 10V, +/-10%, X7R, 0603	MuRata	GRM188R71A225KE15D	1
4	C4, C5	CAP, Film, 0.047uF, 630V, +/-10%, TH	Panasonic	ECQE6473KF	2
5	C6	NA	NA	NA	0
6	C7	CAP, CERM, 2200pF, 250VAC, X1Y1, TH	Murata	DE1E3KX222MA4BL01	1
7	C9	CAP AL, 470uF, 25V, +/-20%, 0.04 ohm, 10x12.5 TH	Panasonic	EEUFR1E471	1
8	D1	Diode, Switching-Bridge, 600V, 0.8A, MiniDIP	Diodes Inc.	RH06-T	1
9	D3	Diode 150V, 0.2A, 50nS, SOD-123	Diodes Inc.	BAV20W-7-F	1
10	D4	Diode, Ultrafast, 75V, 0.15A, SOD-523F	Comchip	CDSU4148	1
11	D5	Diode, TVS, 250V, 400W, SMA	Littelfuse	SMAJ250ALFCT	1
12	D6	Diode, Ultrafast, 600V, 1A, SMA	Diodes Inc.	US1J-13-F	1
13	D7	Diode, Schottky, 100V, 2A, SMA	ST	STPS2H100A	1
14	F1	Fuse - 677_Series, Slo-Blo, 0.5A, 250V, VDE, UL, CSA, CCC	Littelfuse	0677.500	1
15	L1	Inductor, Drum Ferrite 3.3mH 0.1A, 11ohm, TH1	Murata	22R335C	1
16	Q1	MOSFET N-CH, 2.5A, 800V, 4.5ohm, 19nC	ST	STD3NK80Z-1	1
17	R1, R2	RES Metal Film, 15ohm, 5%, 1W, TH	Panasonic	ERG-1SJ150	2
18	R3, R4	RES, 150k ohm, 5%, 0.25W, 1206	Vishay-Dale	CRCW1206150KJNEA	2
19	R5	RES, 100 ohm, 1%, 0.125W, 0805	Vishay-Dale	CRCW0805100RFKEA	1
20	R6	RES, 27.4k ohm, 1%, 0.1W, 0603	Vishay-Dale	CRCW060327K4FKEA	1
21	R7	RES, 66.5k ohm, 1%, 0.25W, 1206	Vishay-Dale	CRCW120666K5FKEA	1
22	R8	RES, 10.5k ohm, 1%, 0.1W, 0603	Vishay-Dale	CRCW060310K5FKEA	1
23	R9	RES, 15.0k ohm, 1%, 0.25W, 1206	Vishay-Dale	CRCW120615K0FKEA	1
24	R10	RES, 1.00k ohm, 1%, 0.1W, 0603	Vishay-Dale	CRCW06031K00FKEA	1
25	R12	RES, 0 ohm, 5%, 0.25W, 1206	Vishay-Dale	CRCW12060000Z0EA	1
26	R13	RES, 3.16 ohm, 1%, 0.25W, 1206	Vishay-Dale	CRCW12063R16FKEA	1
27	R14	NA	NA	NA	0
28	R15	NA	NA	NA	0
29	T1	Transformer EE-13	Wurth Midcom	750341569	1
30	U1	Off-Line Primary Side Sensing Controller with PFC	Texas Instruments	TPS92314	1
31	VDR1	Varistor 275V	EPCOS	S07K275E2	1

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